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(12) **United States Design Patent**
Takebayashi et al.

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(54) **BOAT OF WAFER PROCESSING APPARATUS**

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(30) **Foreign Application Priority Data**

Jun. 18, 2010 (JP) 2010-015045

(51) **LOC (9) Cl.** **13-03**

(52) **U.S. Cl.** **D13/182**

(58) **Field of Classification Search** D13/182;
D15/144, 144.1, 199; 118/715; 211/41.18;
432/253, 258

See application file for complete search history.

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(57) **CLAIM**

The ornamental design for a boat of a wafer processing apparatus, as shown and described.

DESCRIPTION

FIG. 1 is a perspective view 1 of a boat of the wafer processing apparatus;
FIG. 2 is a front elevational view thereof;
FIG. 3 is a rear elevational view thereof;
FIG. 4 is a right side elevational view thereof;
FIG. 5 is a left side elevational view thereof;
FIG. 6 is a top plan view thereof;
FIG. 7 is a bottom plan view thereof;
FIG. 8 is an enlarged cross-sectional view thereof taken along lines 8-8 in FIG. 2;
FIG. 9 is a cross-sectional view thereof taken along lines 9-9 in FIG. 8; and,
FIG. 10 is a perspective view of the cross-section from FIG. 9. The broken line showing of the boat of a wafer processing apparatus is for the purpose of illustrating environmental structure and forms no part of the claimed design.

1 Claim, 10 Drawing Sheets

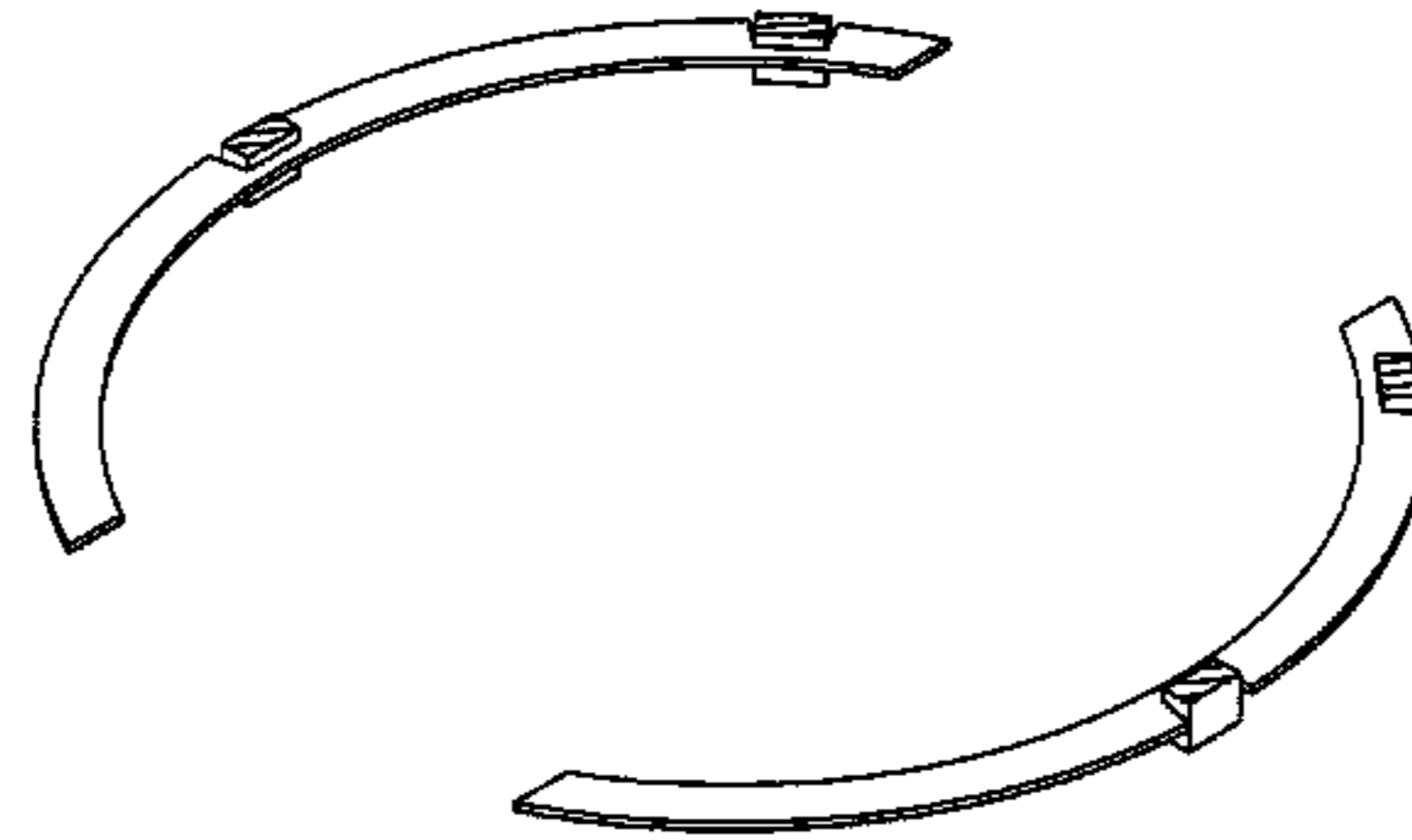
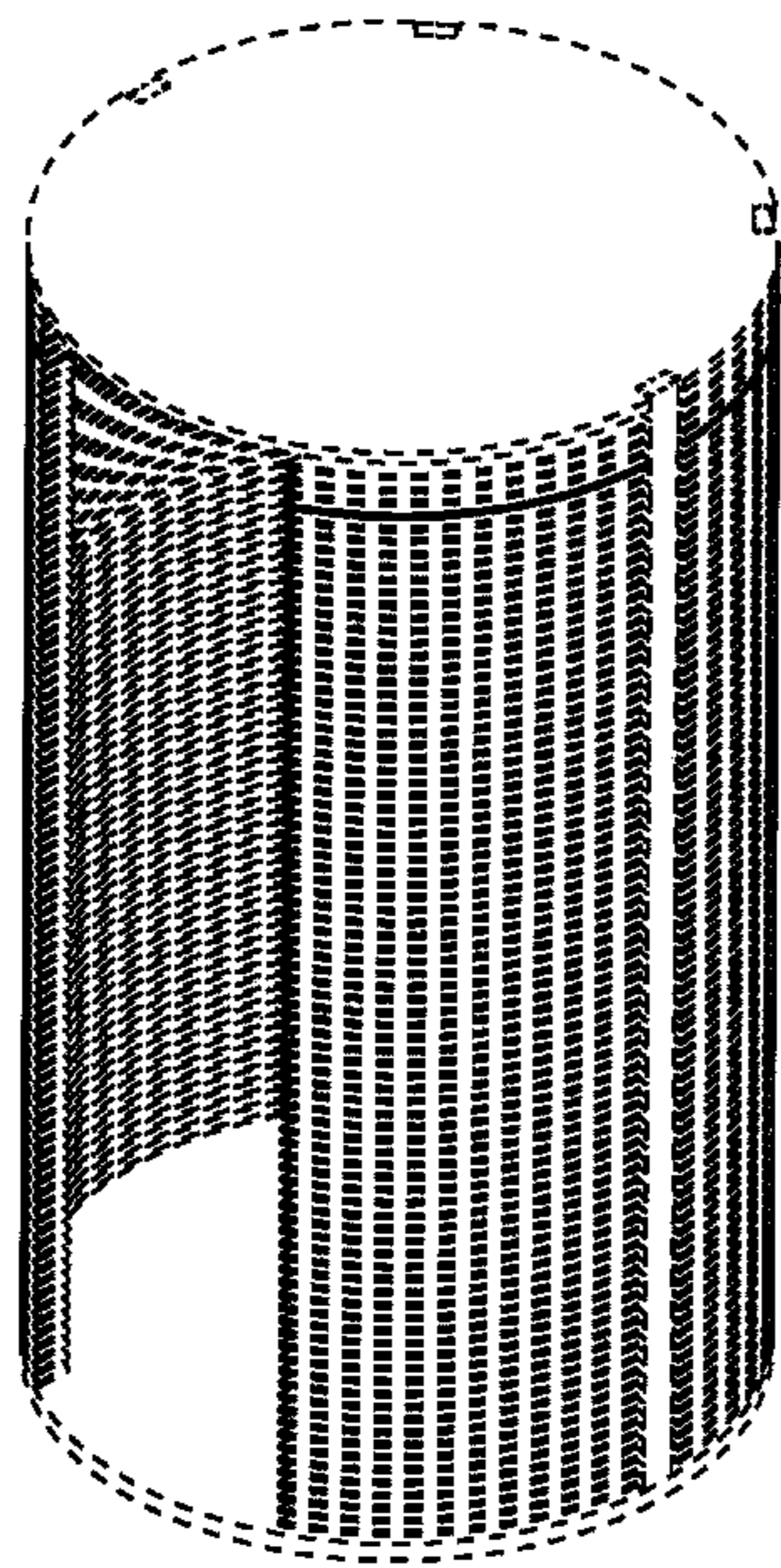


Fig. 1

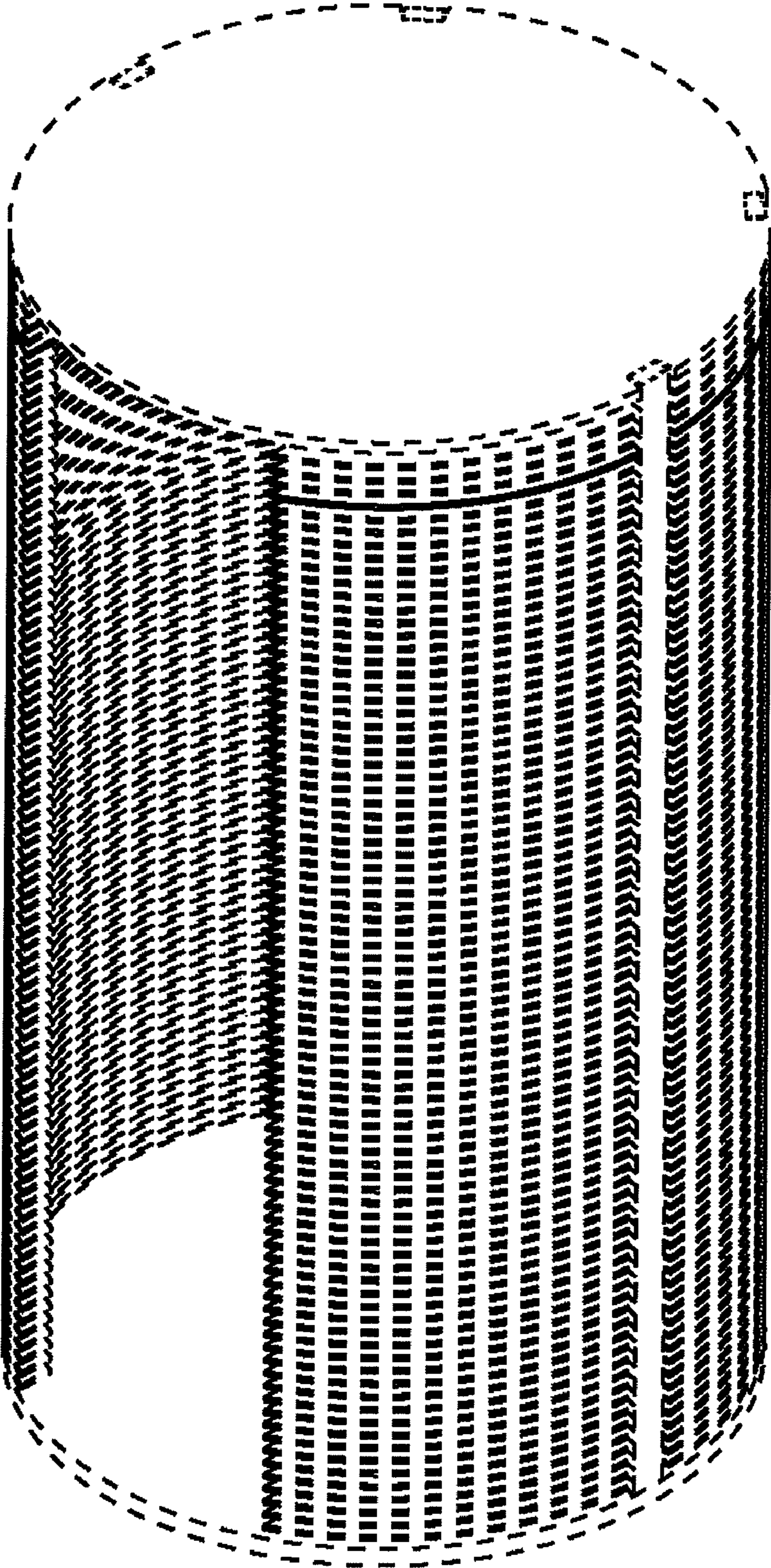


Fig. 2

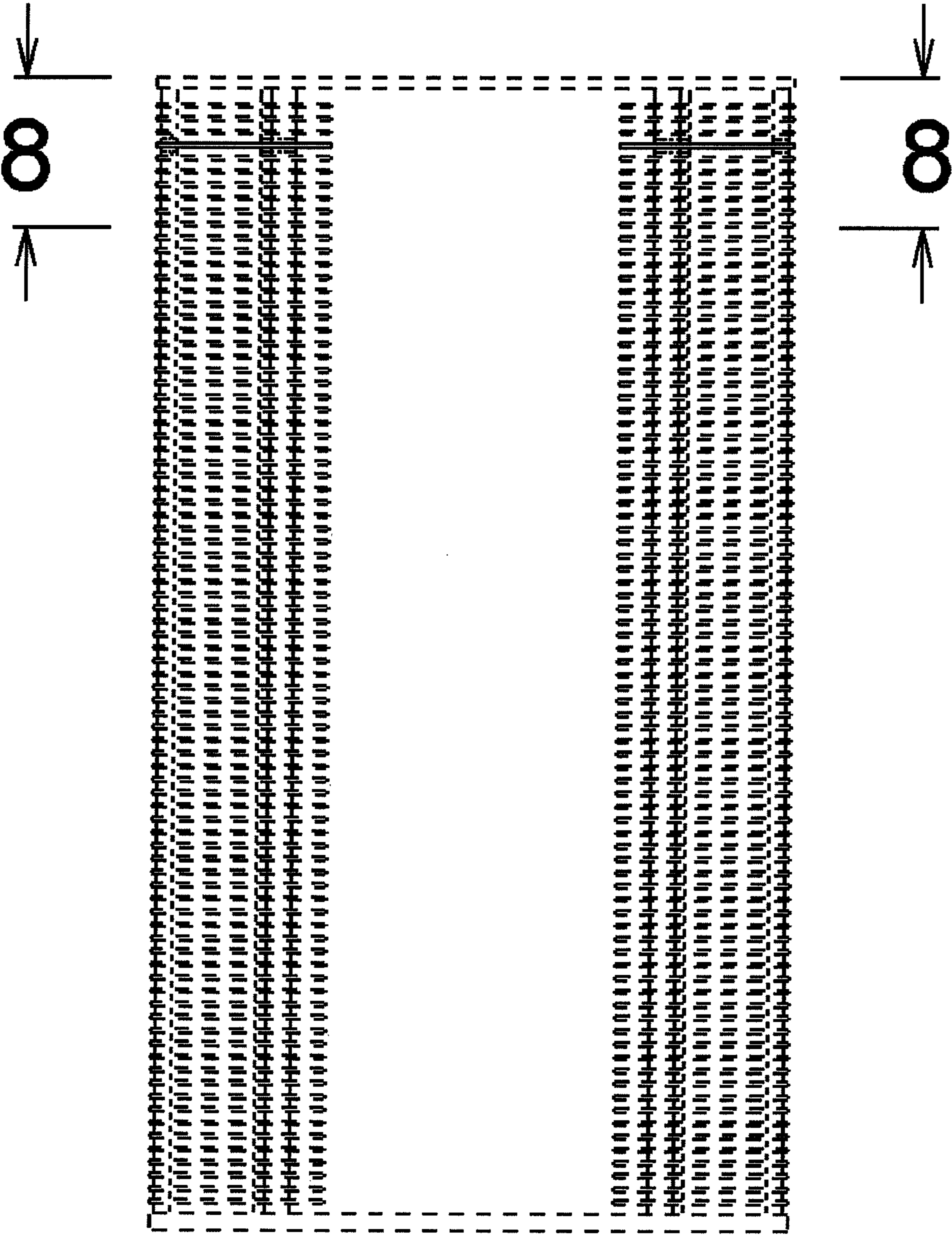


Fig. 3

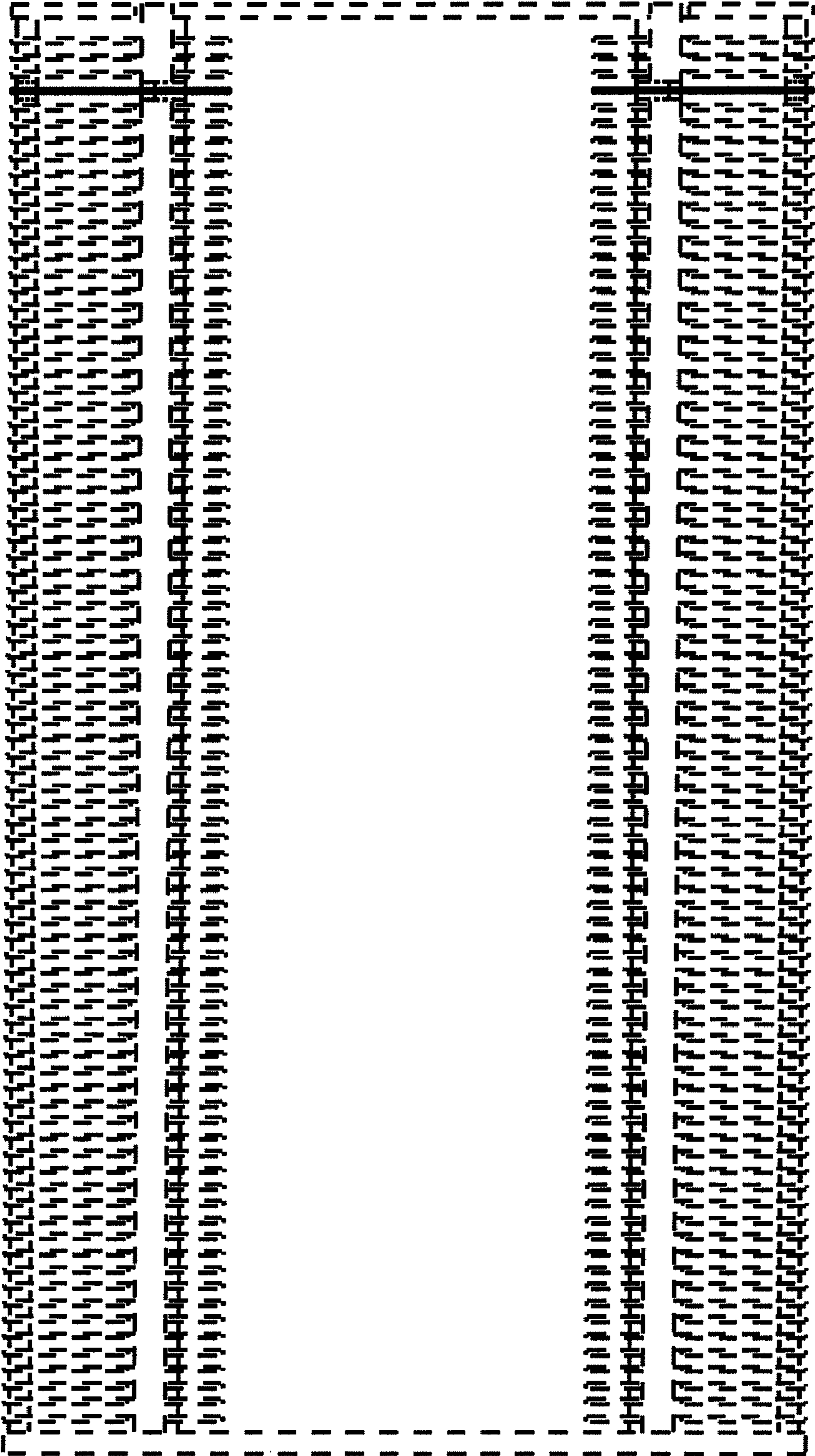


Fig. 4

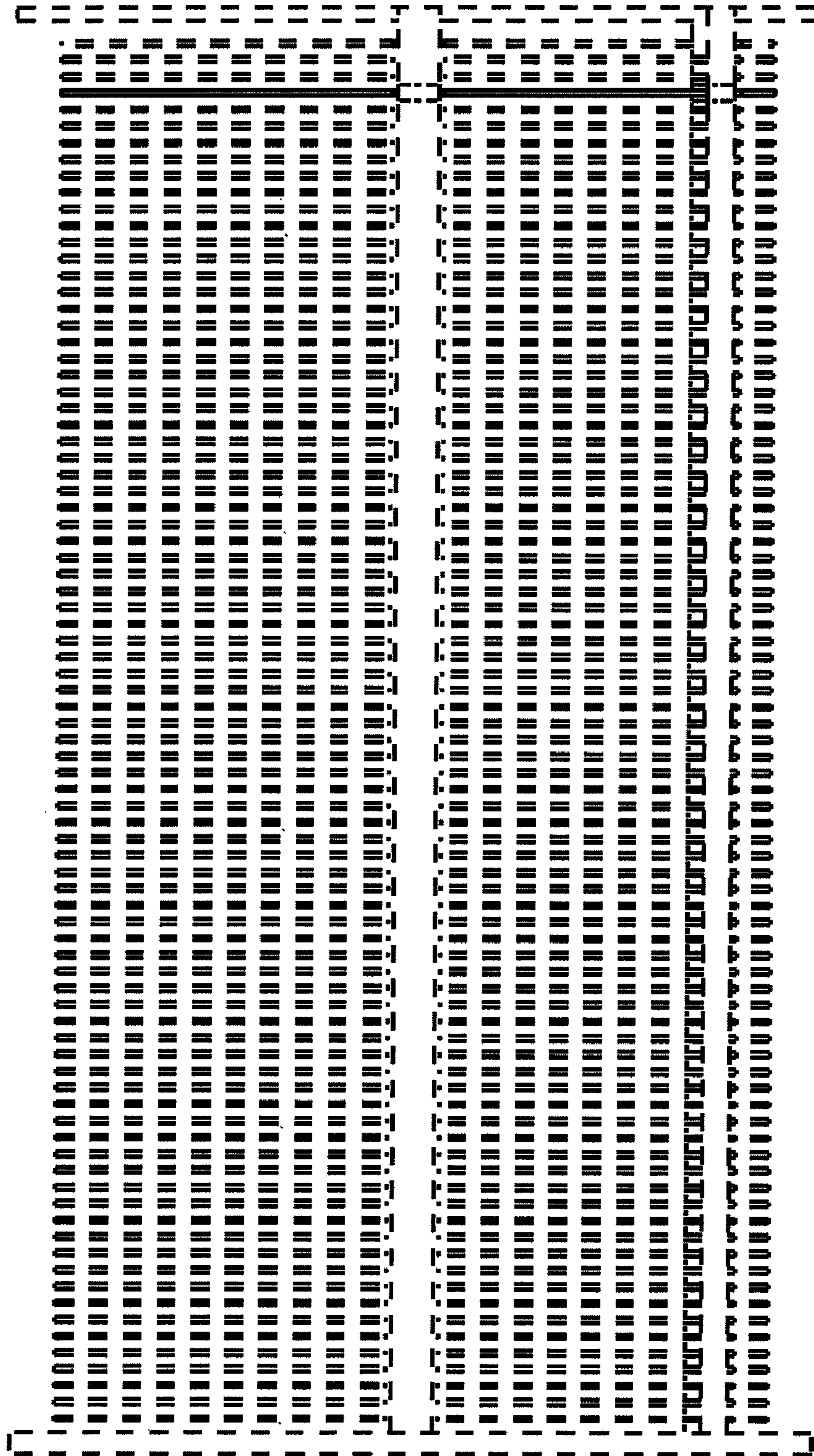


Fig. 5

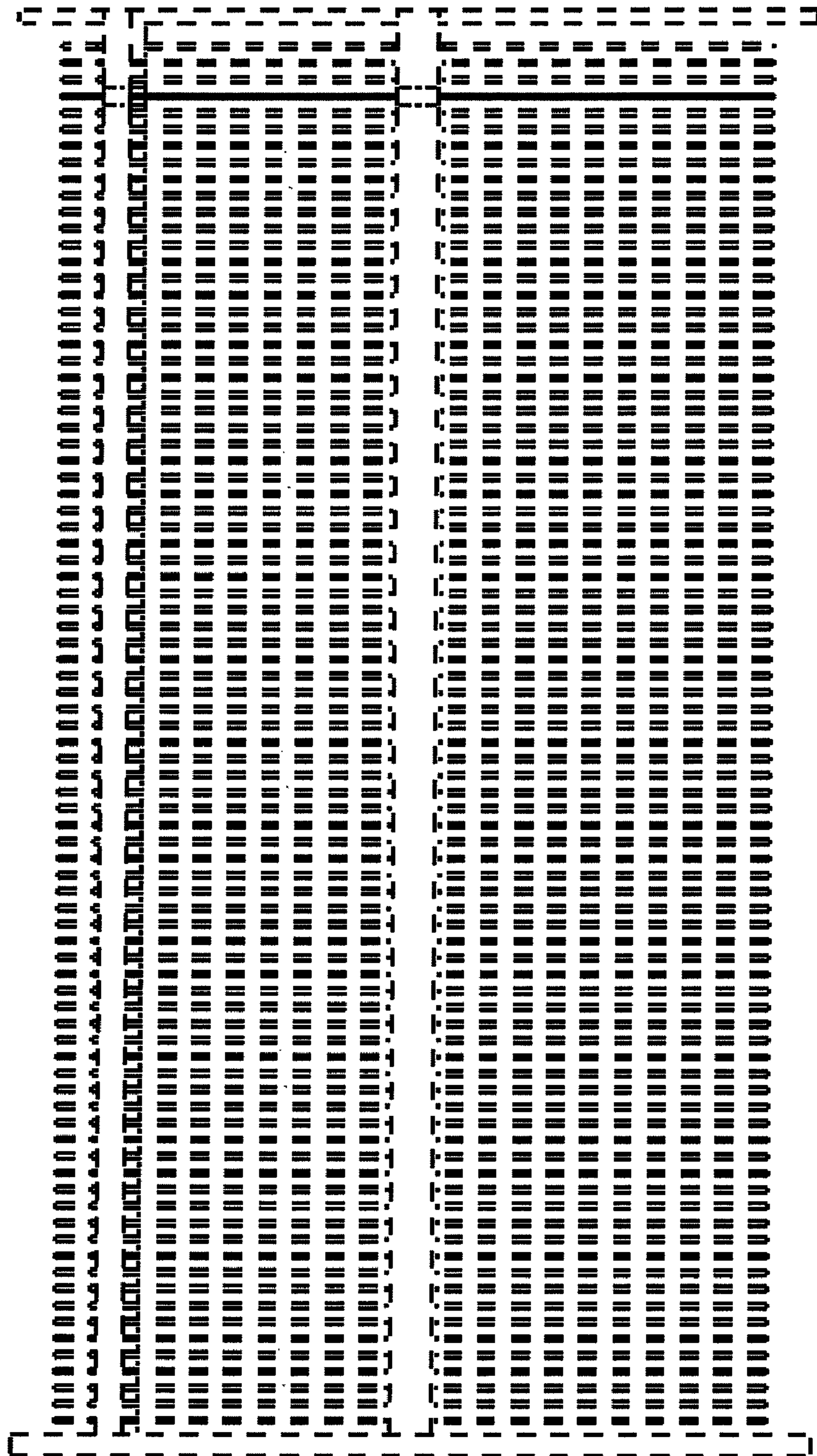


Fig. 6

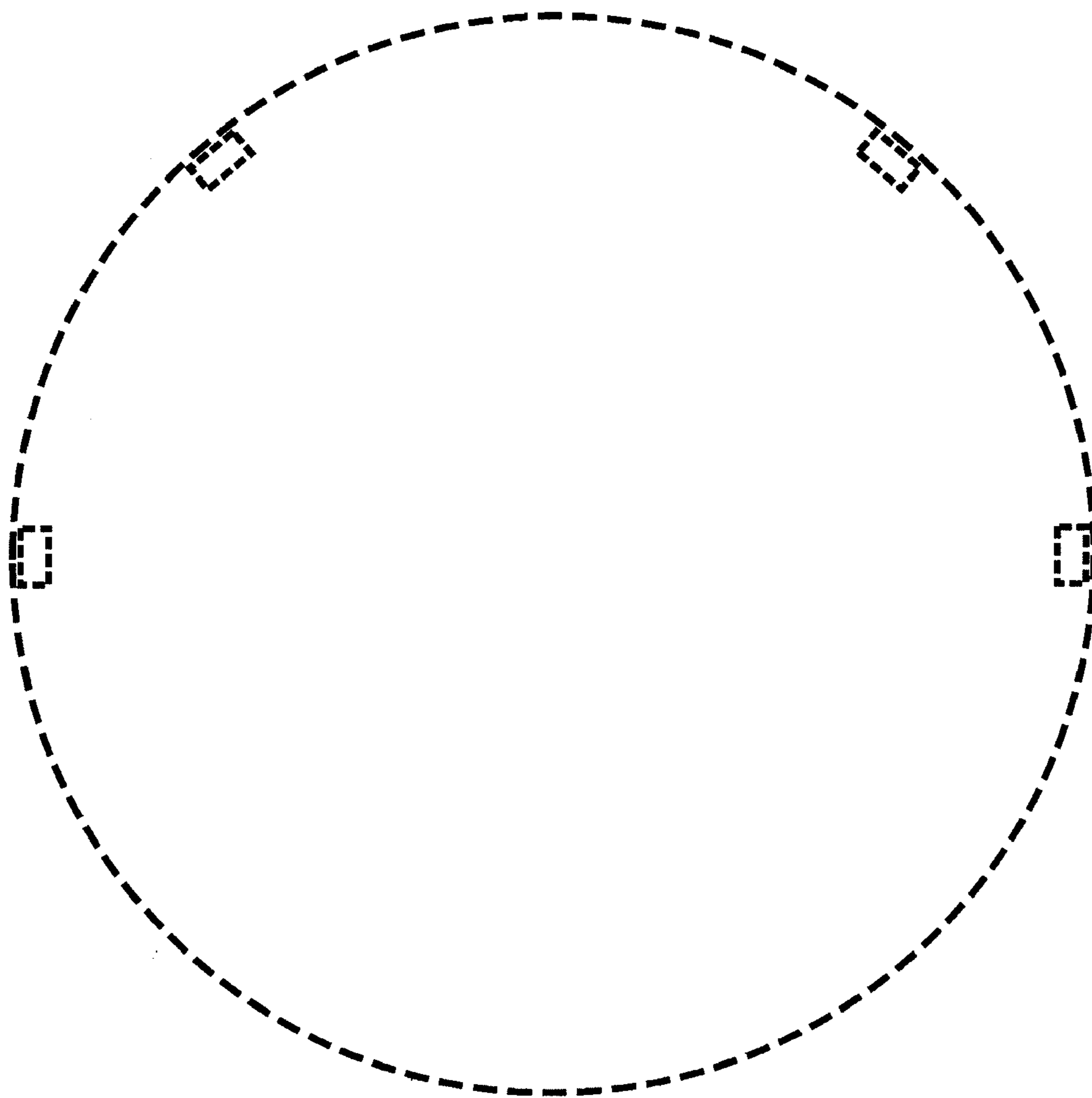
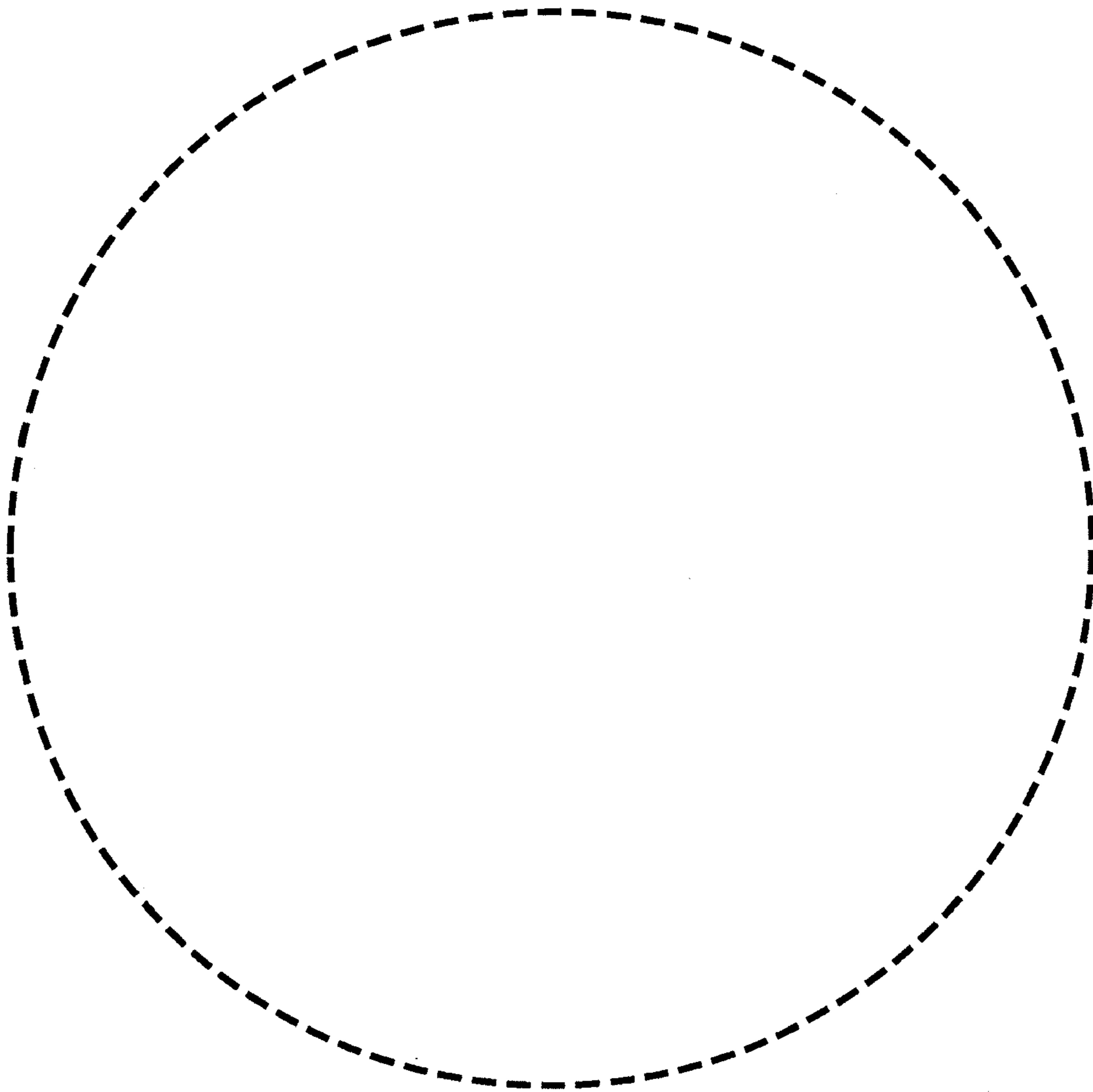


Fig. 7



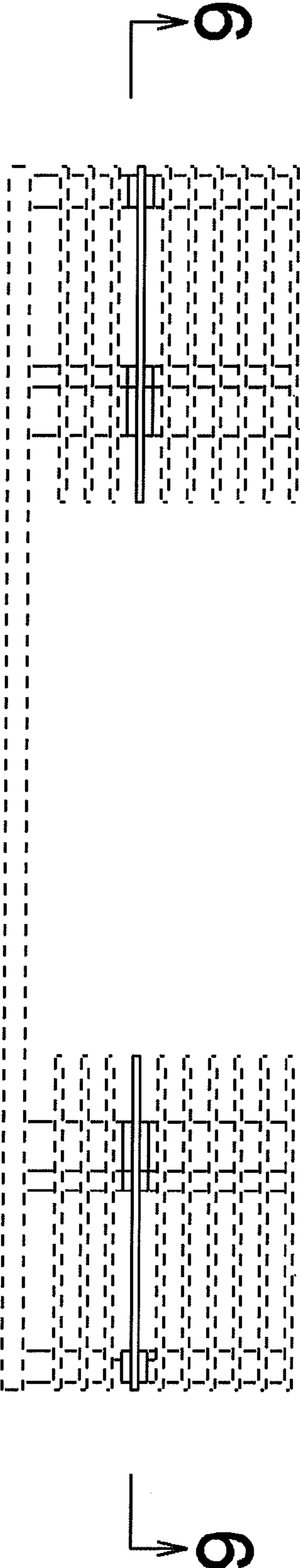


Fig. 8

Fig. 9

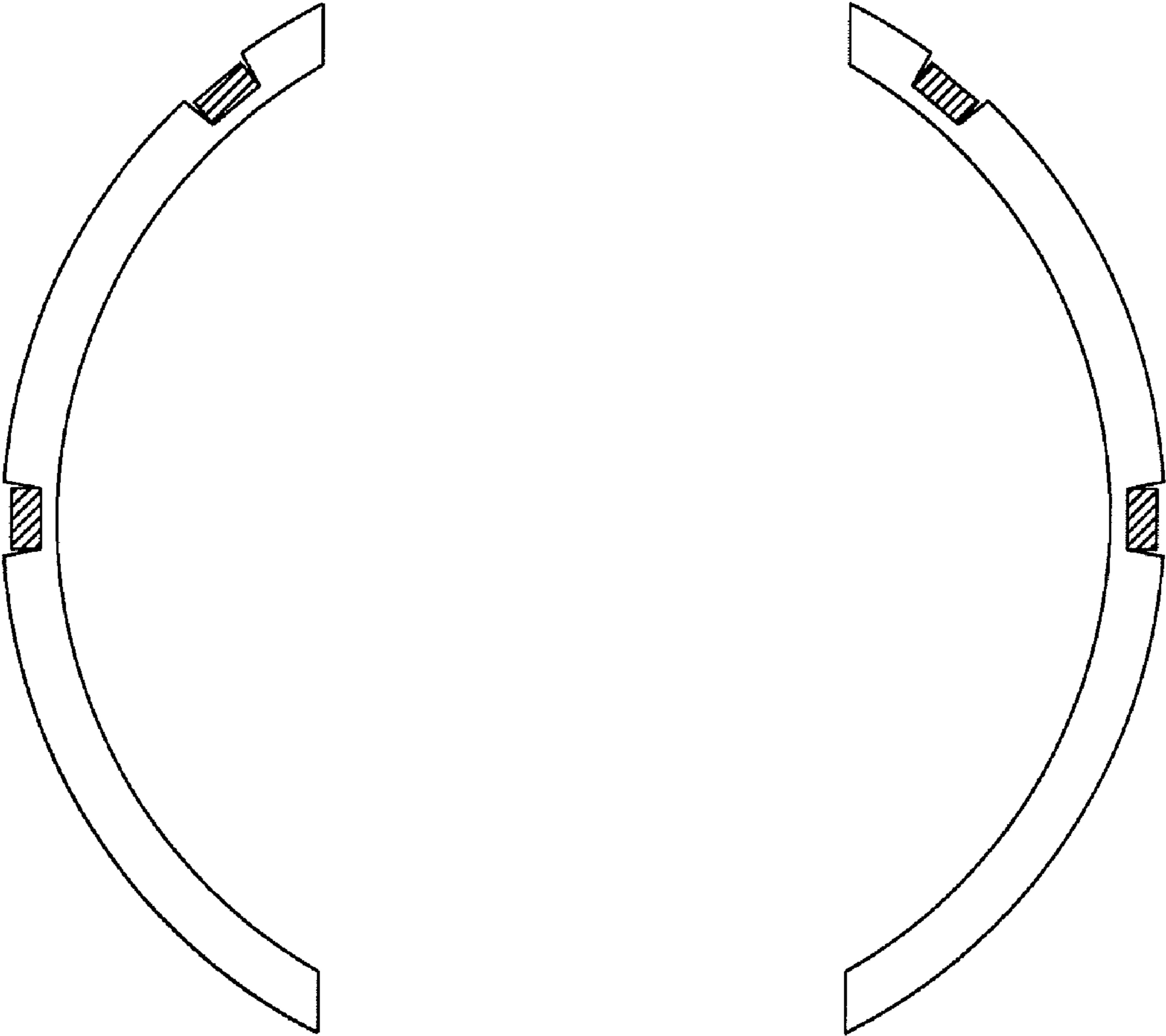


Fig. 10

